

# NGTG50N60FWG

## IGBT

This Insulated Gate Bipolar Transistor (IGBT) features a robust and cost effective Trench construction, and provides superior performance in demanding switching applications, offering both low on state voltage and minimal switching loss.

### Features

- Optimized for Very Low  $V_{CEsat}$
- Low Switching Loss Reduces System Power Dissipation
- 5  $\mu$ s Short-Circuit Capability
- These are Pb-Free Devices

### Typical Applications

- Solar Inverters
- Uninterruptible Power Supplies (UPS)
- Motor Drives

### ABSOLUTE MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector-emitter voltage	$V_{CES}$	600	V
Collector current @ $T_c = 25^\circ\text{C}$ @ $T_c = 100^\circ\text{C}$	$I_c$	100 50	A
Pulsed collector current, $T_{pulse}$ limited by $T_{Jmax}$	$I_{CM}$	200	A
Short-circuit withstand time $V_{GE} = 15\text{ V}$ , $V_{CE} = 300\text{ V}$ , $T_J \leq +150^\circ\text{C}$	$t_{SC}$	5	$\mu$ s
Gate-emitter voltage Transient Gate-Emitter Voltage	$V_{GE}$	$\pm 20$ $\pm 30$	V
Power Dissipation @ $T_c = 25^\circ\text{C}$ @ $T_c = 100^\circ\text{C}$	$P_d$	223 89	W
Operating junction temperature range	$T_J$	-55 to +150	$^\circ\text{C}$
Storage temperature range	$T_{stg}$	-55 to +150	$^\circ\text{C}$
Lead temperature for soldering, 1/8" from case for 5 seconds	$T_{SLD}$	260	$^\circ\text{C}$

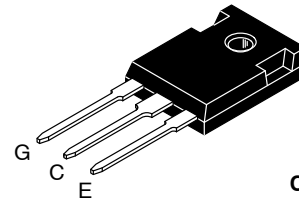
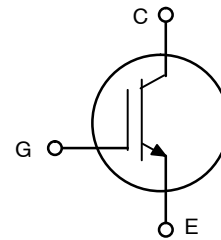
Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.



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**50 A, 600 V**  
 **$V_{CEsat} = 1.50\text{ V}$**



**TO-247  
CASE 340L  
STYLE 4**

### MARKING DIAGRAM



- A = Assembly Location
- Y = Year
- WW = Work Week
- G = Pb-Free Package

### ORDERING INFORMATION

Device	Package	Shipping
NGTG50N60FWG	TO-247 (Pb-Free)	30 Units / Rail

# NGTG50N60FWG

## THERMAL CHARACTERISTICS

Rating	Symbol	Value	Unit
Thermal resistance junction-to-case, for IGBT	$R_{\theta JC}$	0.56	$^{\circ}\text{C}/\text{W}$
Thermal resistance junction-to-ambient	$R_{\theta JA}$	40	$^{\circ}\text{C}/\text{W}$

## ELECTRICAL CHARACTERISTICS ( $T_J = 25^{\circ}\text{C}$ unless otherwise specified)

Parameter	Test Conditions	Symbol	Min	Typ	Max	Unit
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### STATIC CHARACTERISTIC

Collector-emitter breakdown voltage, gate-emitter short-circuited	$V_{GE} = 0\text{ V}, I_C = 500\ \mu\text{A}$	$V_{(BR)CES}$	600	-	-	V
Collector-emitter saturation voltage	$V_{GE} = 15\text{ V}, I_C = 50\text{ A}$ $V_{GE} = 15\text{ V}, I_C = 50\text{ A}, T_J = 150^{\circ}\text{C}$	$V_{CEsat}$	1.25 -	1.45 1.7	1.7 -	V
Gate-emitter threshold voltage	$V_{GE} = V_{CE}, I_C = 350\ \mu\text{A}$	$V_{GE(th)}$	4.5	5.5	6.5	V
Collector-emitter cut-off current, gate-emitter short-circuited	$V_{GE} = 0\text{ V}, V_{CE} = 600\text{ V}$ $V_{GE} = 0\text{ V}, V_{CE} = 600\text{ V}, T_J = 150^{\circ}\text{C}$	$I_{CES}$	-	-	0.5 2	mA
Gate leakage current, collector-emitter short-circuited	$V_{GE} = 20\text{ V}, V_{CE} = 0\text{ V}$	$I_{GES}$	-	-	200	nA

### DYNAMIC CHARACTERISTIC

Input capacitance	$V_{CE} = 20\text{ V}, V_{GE} = 0\text{ V}, f = 1\text{ MHz}$	$C_{ies}$	-	7300	-	pF
Output capacitance		$C_{oes}$	-	195	-	
Reverse transfer capacitance		$C_{res}$	-	170	-	
Gate charge total	$V_{CE} = 480\text{ V}, I_C = 50\text{ A}, V_{GE} = 15\text{ V}$	$Q_g$	-	310	-	nC
Gate to emitter charge		$Q_{ge}$	-	60	-	
Gate to collector charge		$Q_{gc}$	-	150	-	

### SWITCHING CHARACTERISTIC, INDUCTIVE LOAD

Turn-on delay time	$T_J = 25^{\circ}\text{C}$ $V_{CC} = 400\text{ V}, I_C = 50\text{ A}$ $R_g = 10\ \Omega$ $V_{GE} = 0\text{ V}/15\text{ V}^*$	$t_{d(on)}$	-	117	-	ns	
Rise time		$t_r$	-	43	-		
Turn-off delay time		$t_{d(off)}$	-	285	-		
Fall time			$t_f$	-	105	-	mJ
Turn-on switching loss		$E_{on}$	-	1.1	-		
Turn-off switching loss		$E_{off}$	-	1.2	-		
Total switching loss		$E_{ts}$	-	2.3	-		
Turn-on delay time	$T_J = 150^{\circ}\text{C}$ $V_{CC} = 400\text{ V}, I_C = 50\text{ A}$ $R_g = 10\ \Omega$ $V_{GE} = 0\text{ V}/15\text{ V}^*$	$t_{d(on)}$	-	112	-	ns	
Rise time		$t_r$	-	45	-		
Turn-off delay time		$t_{d(off)}$	-	300	-		
Fall time			$t_f$	-	214	-	mJ
Turn-on switching loss		$E_{on}$	-	1.4	-		
Turn-off switching loss		$E_{off}$	-	2.0	-		
Total switching loss		$E_{ts}$	-	3.4	-		

\*Includes diode reverse recovery loss using NGTB50N60FWG.

# NGTG50N60FWG

## TYPICAL CHARACTERISTICS

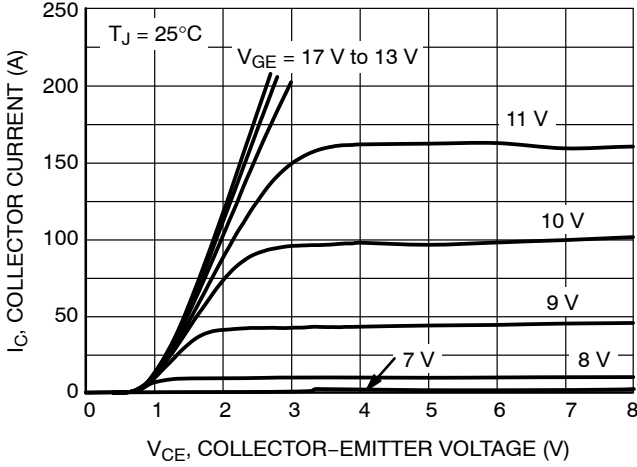


Figure 1. Output Characteristics

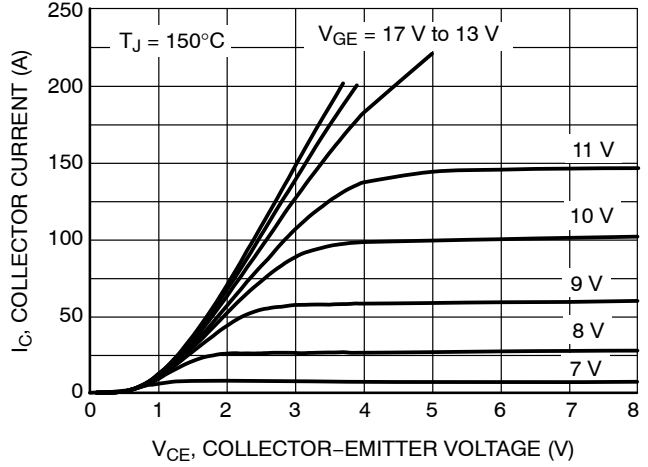


Figure 2. Output Characteristics

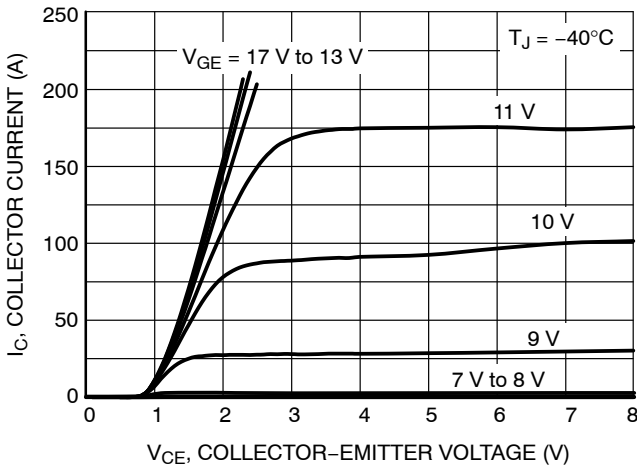


Figure 3. Output Characteristics

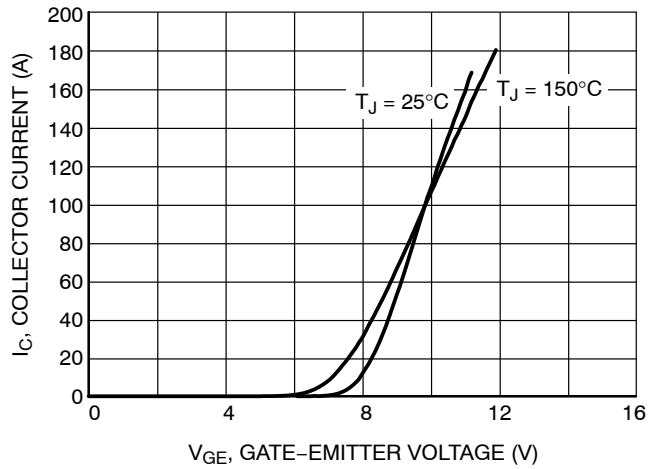


Figure 4. Typical Transfer Characteristics

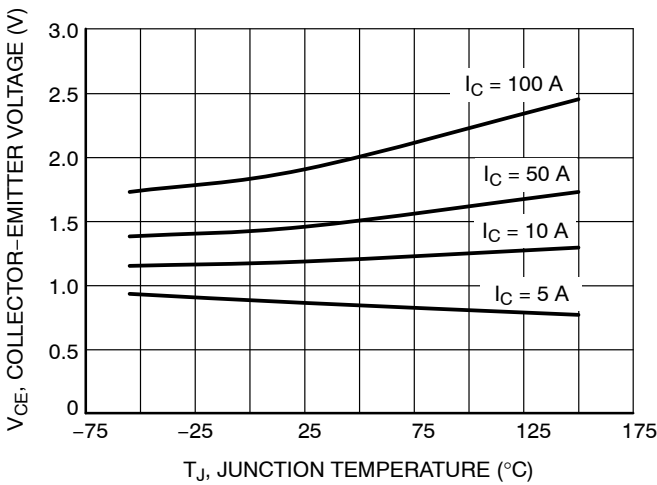


Figure 5.  $V_{CE(sat)}$  vs.  $T_J$

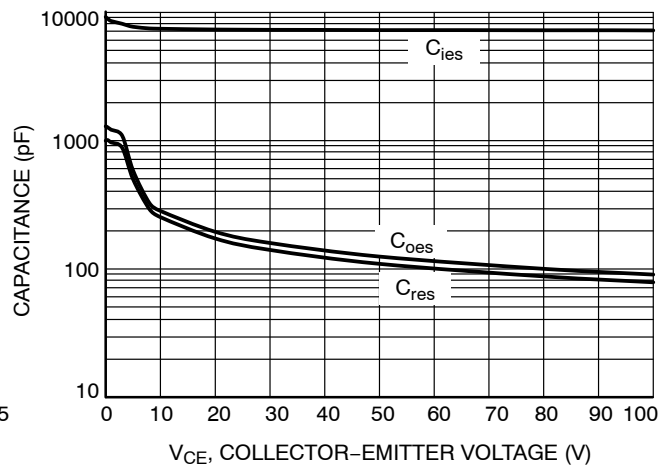


Figure 6. Typical Capacitance

# NGTG50N60FWG

## TYPICAL CHARACTERISTICS

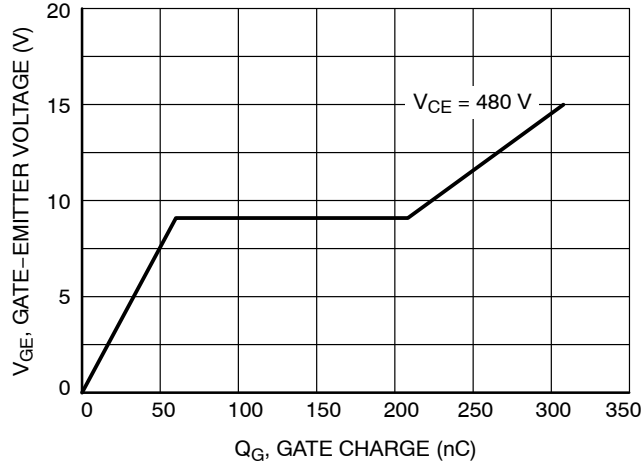


Figure 7. Typical Gate Charge

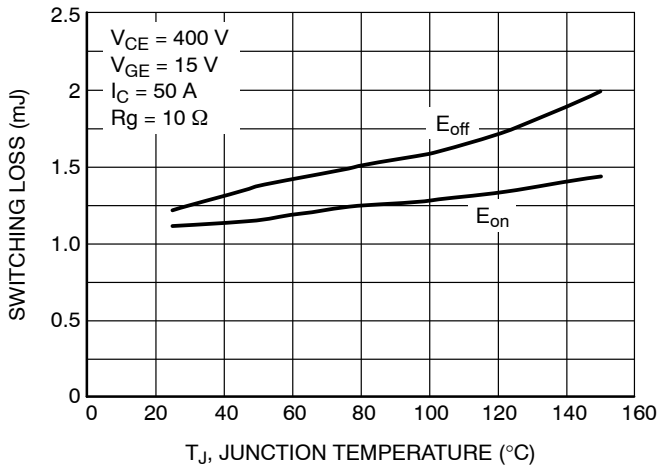


Figure 8. Switching Loss vs. Temperature

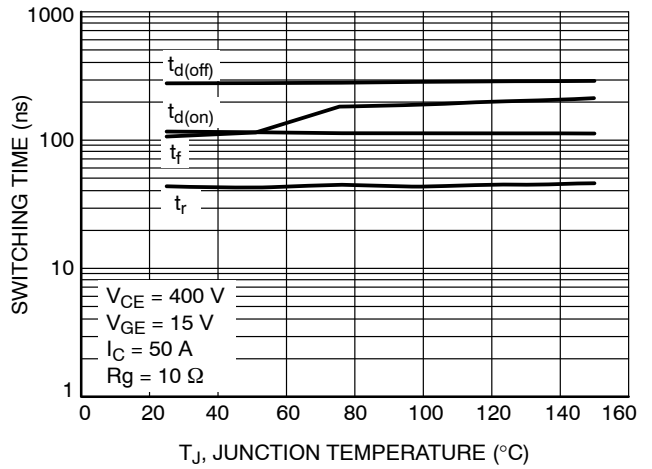


Figure 9. Switching Time vs. Temperature

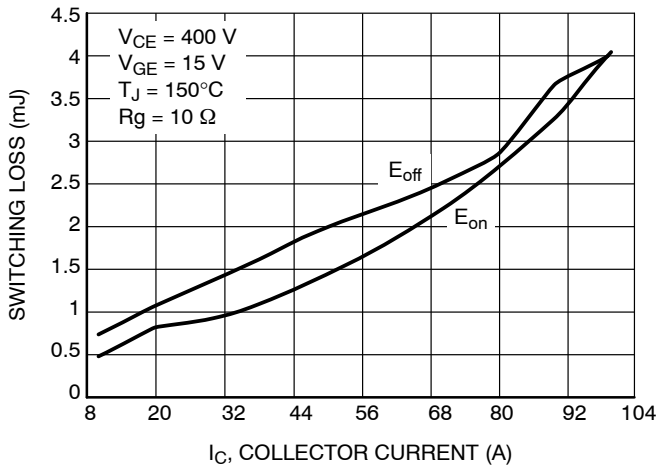


Figure 10. Switching Loss vs.  $I_C$

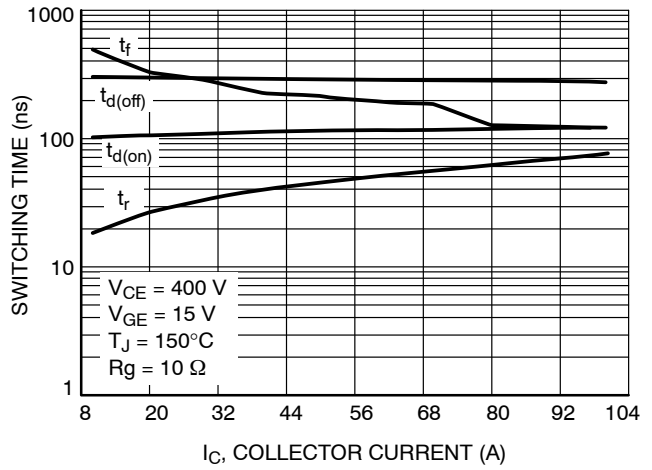


Figure 11. Switching Time vs.  $I_C$

# NGTG50N60FWG

## TYPICAL CHARACTERISTICS

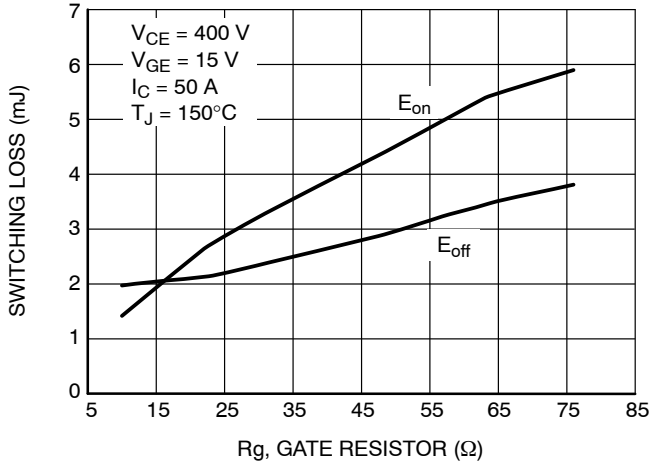


Figure 12. Switching Loss vs. Rg

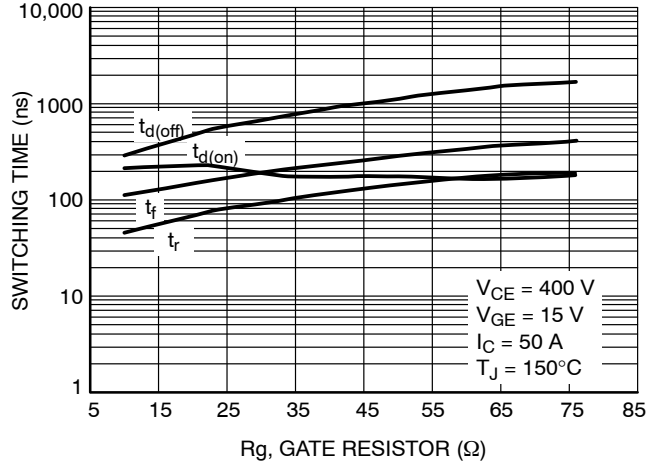


Figure 13. Switching Time vs. Rg

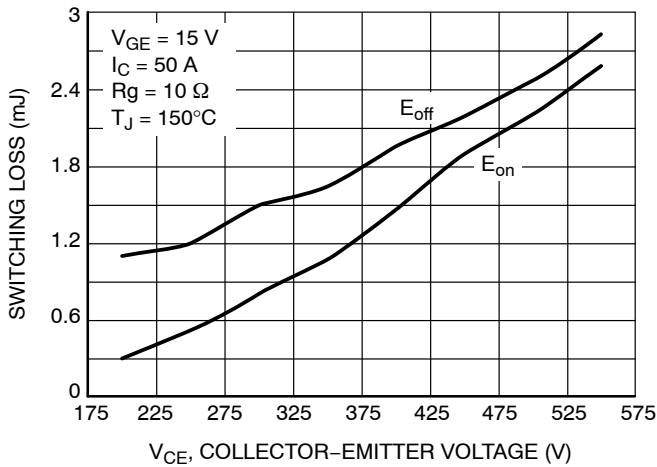


Figure 14. Switching Loss vs.  $V_{CE}$

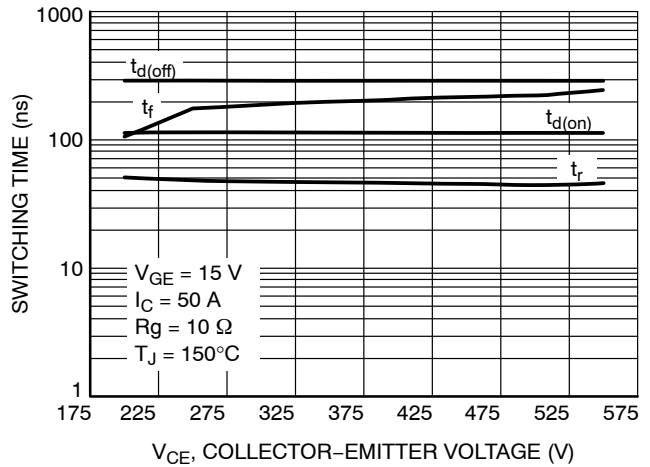


Figure 15. Switching Time vs.  $V_{CE}$

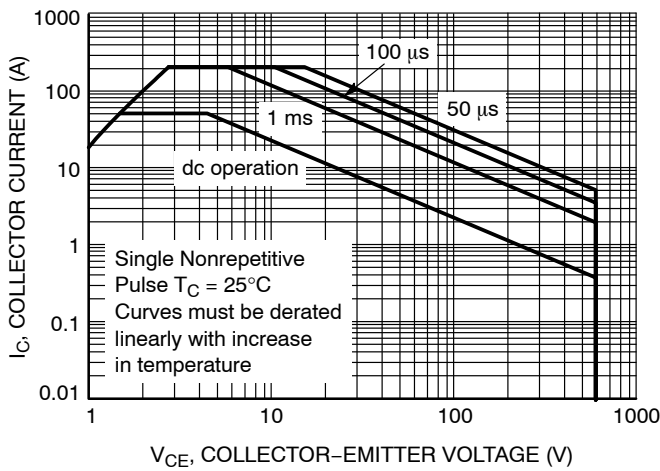


Figure 16. Safe Operating Area

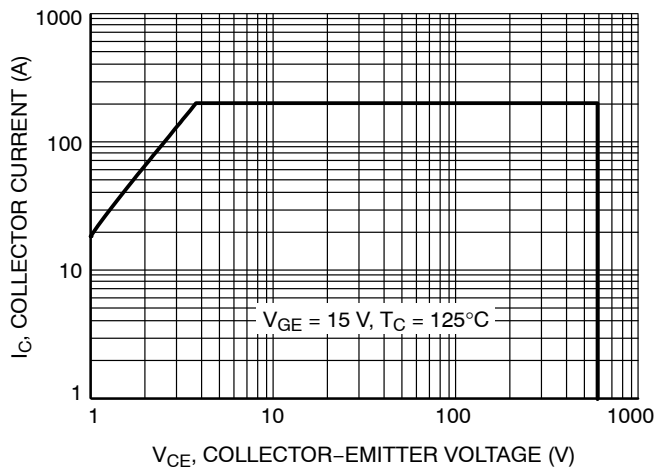


Figure 17. Reverse Bias Safe Operating Area

# NGTG50N60FWG

## TYPICAL CHARACTERISTICS

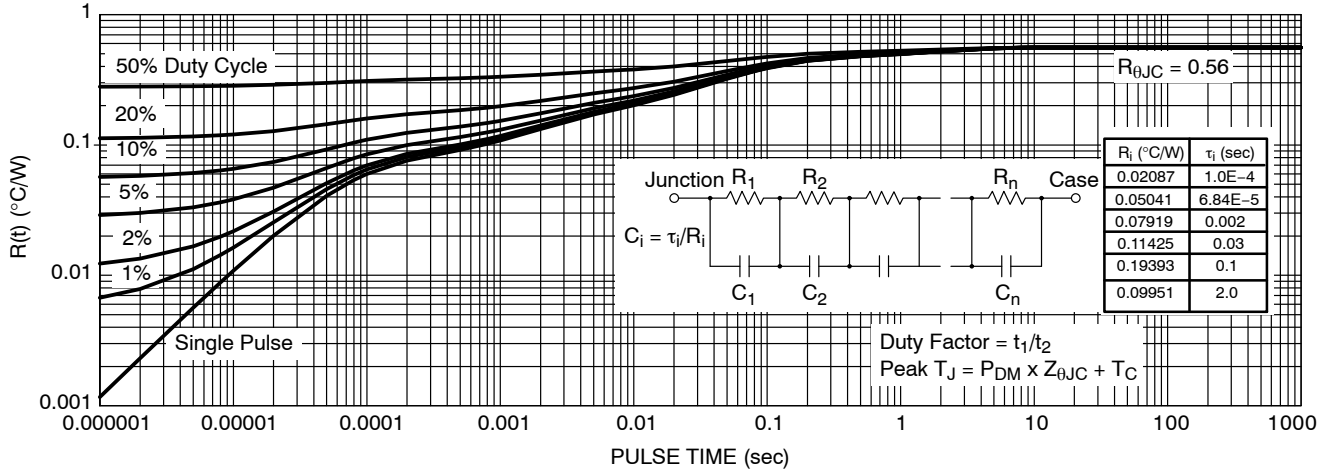


Figure 18. IGBT Transient Thermal Impedance

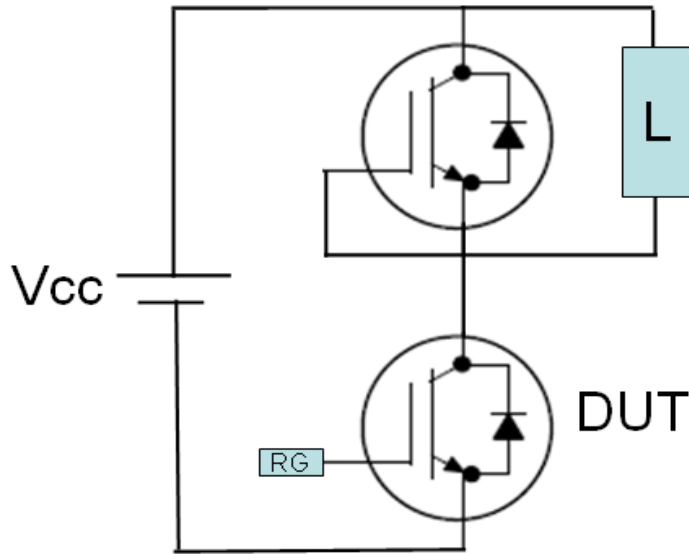


Figure 19. Test Circuit for Switching Characteristics

# NGTG50N60FWG

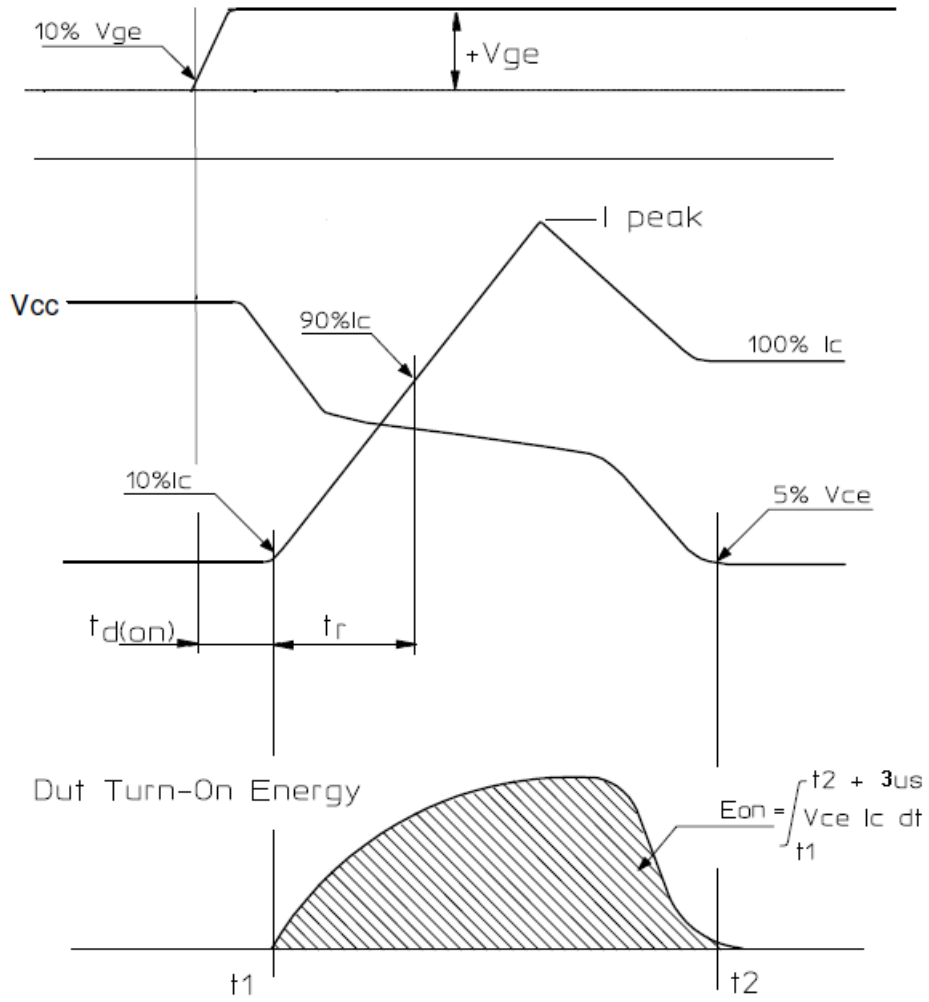


Figure 20. Definition of Turn On Waveform

# NGTG50N60FWG

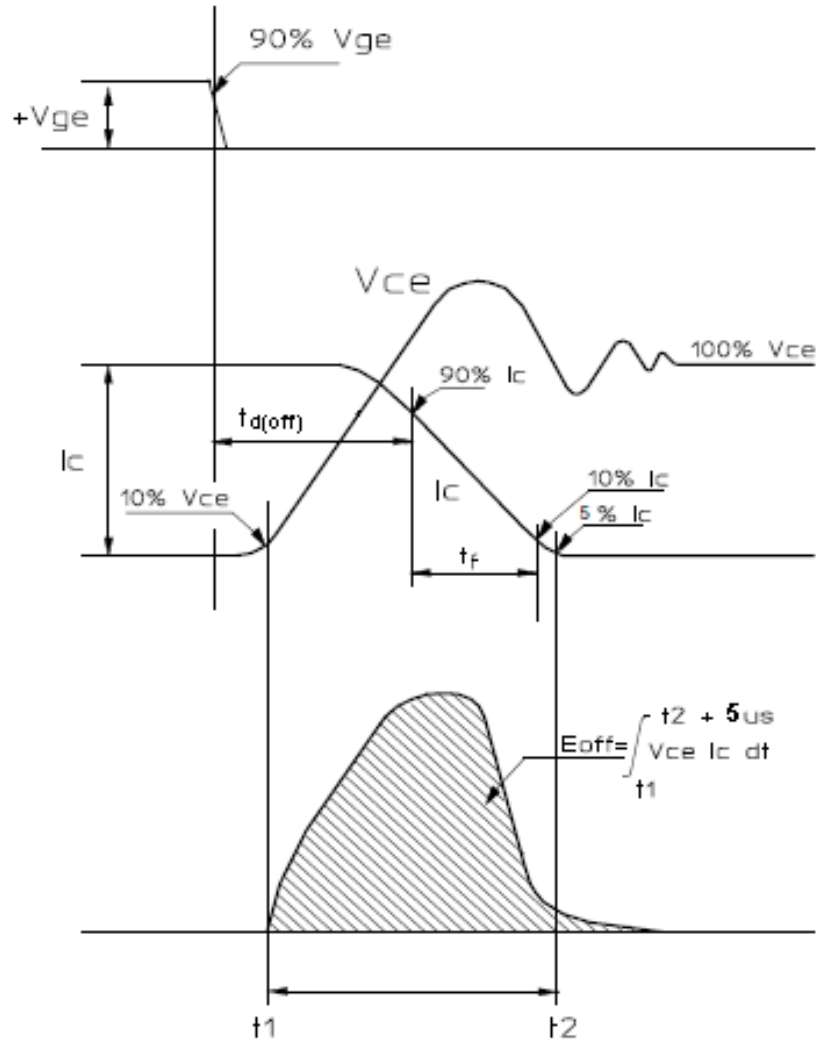
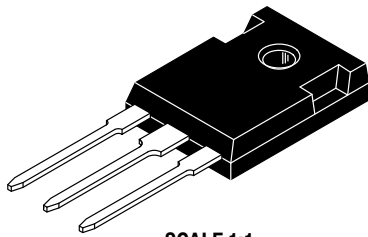


Figure 21. Definition of Turn Off Waveform



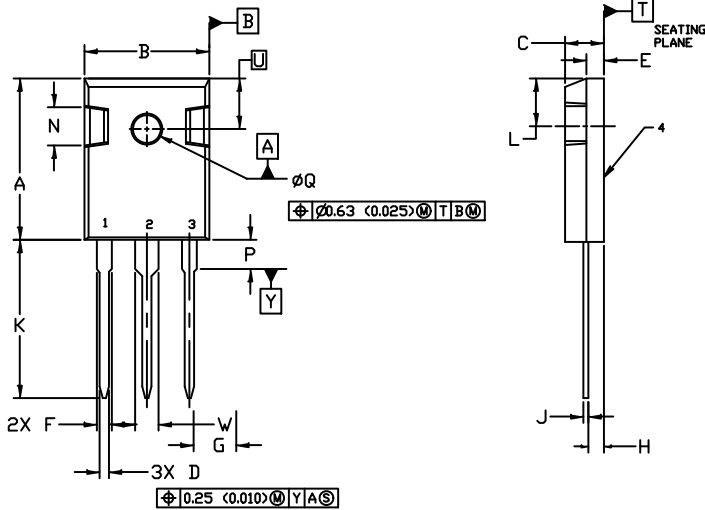
# MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



TO-247  
CASE 340L  
ISSUE G

DATE 06 OCT 2021

SCALE 1:1

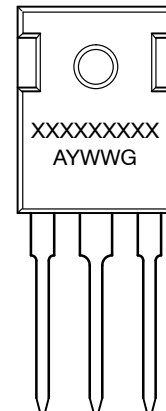


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER

DIM	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	20.32	21.08	0.800	0.830
B	15.75	16.26	0.620	0.640
C	4.70	5.30	0.185	0.209
D	1.00	1.40	0.040	0.055
E	1.90	2.60	0.075	0.102
F	1.65	2.13	0.065	0.084
G	5.45 BSC		0.215 BSC	
H	1.50	2.49	0.059	0.098
J	0.40	0.80	0.016	0.031
K	19.81	20.83	0.780	0.820
L	5.40	6.20	0.212	0.244
N	4.32	5.49	0.170	0.216
P	----	4.50	----	0.177
Q	3.55	3.65	0.140	0.144
U	6.15 BSC		0.242 BSC	
W	2.87	3.12	0.113	0.123

GENERIC  
MARKING DIAGRAM\*



- |  |  |  |  |
|--|--|--|--|
| <p>STYLE 1:<br/>PIN 1. GATE<br/>2. DRAIN<br/>3. SOURCE<br/>4. DRAIN</p>  | <p>STYLE 2:<br/>PIN 1. ANODE<br/>2. CATHODE (S)<br/>3. ANODE 2<br/>4. CATHODES (S)</p>               | <p>STYLE 3:<br/>PIN 1. BASE<br/>2. COLLECTOR<br/>3. EMITTER<br/>4. COLLECTOR</p> | <p>STYLE 4:<br/>PIN 1. GATE<br/>2. COLLECTOR<br/>3. EMITTER<br/>4. COLLECTOR</p> |
| <p>STYLE 5:<br/>PIN 1. CATHODE<br/>2. ANODE<br/>3. GATE<br/>4. ANODE</p> | <p>STYLE 6:<br/>PIN 1. MAIN TERMINAL 1<br/>2. MAIN TERMINAL 2<br/>3. GATE<br/>4. MAIN TERMINAL 2</p> |  |  |

- XXXXXX = Specific Device Code  
A = Assembly Location  
Y = Year  
WW = Work Week  
G = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

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DESCRIPTION:	TO-247	PAGE 1 OF 1

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